9+2-Bit Parity Generator/ Checker

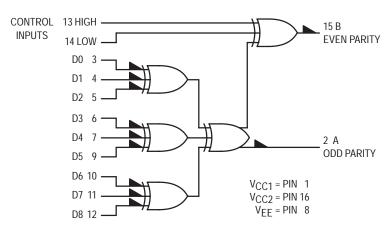
The MC10170 is a 11-bit parity circuit, which is segmented into 9 data bits and 2 control bits.

Output A generates odd parity on 9 bits; that is, Output A goes high for an odd number of high logic levels on the bit inputs in only 2 gate delays.

The Control Inputs can be used to expand parity to larger numbers of bits with minimal delay or can be used to generate even parity. To expand parity to larger words, the MC10170 can be used with the MC10160 or other MC10170's. The MC10170 can generate both even and odd parity.

- $P_D = 300 \text{ mW typ/pkg (No Load)}$
- t_{pd} = 2.5 ns typ (Control Inputs to B Output) 4.0 ns typ (Data Inputs to A Output) 6.0 ns typ (Data Inputs to B Output)
- t_r , $t_f = 2.0$ ns typ (20%–80%)

LOGIC DIAGRAM

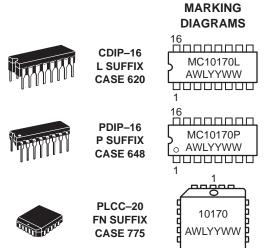


INPUTS	OUTPUTS				
Sum of	Odd Parity	Even Parity			
D Inputs at High Level	Output A	Output B			
Even	Low	High			
Odd	High	Low			



ON Semiconductor

http://onsemi.com

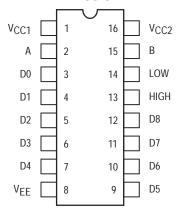


A = Assembly Location

WL = Wafer Lot

YY = Year WW = Work Week

DIP PIN ASSIGNMENT



Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

ORDERING INFORMATION

Device	Package	Shipping
MC10170L	CDIP-16	25 Units / Rail
MC10170P	PDIP-16	25 Units / Rail
MC10170FN	PLCC-20	46 Units / Rail

ELECTRICAL CHARACTERISTICS

					٦	Test Limits	3			
		Pin Under	−30°C		+25°C			+85°C		1
Characteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply Drain Curre	nt I _E	8		78		57	71		78	mAdc
Input Current	linH	3 5		350 350			200 220		220 220	μAdc
	linL	3	0.5		0.5			0.3		μAdc
Output Voltage Log	c1 V _{OH}	2 15	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	Vdc
Output Voltage Log	c 0 V _{OL}	2 15	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	Vdc
Threshold Voltage Log	c1 VOHA	2 15	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		Vdc
Threshold Voltage Log	c 0 VOLA	2 15		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	Vdc
Switching Times (50 Ω Lo	ad)									ns
Propagation Delay	t ₁₃₊₁₅₊ t ₁₄₋₁₅₋ t ₃₊₂₋ t ₃₋₁₅₊	15 15 2 15	1.5 1.5 2.0 4.0	4.2 4.2 6.6 9.5	1.5 1.5 2.0 4.0	2.5 2.5 4.0 6.0	4.0 4.0 6.0 8.8	1.5 1.5 2.0 4.0	4.4 4.4 6.6 9.5	
Rise Time (20 to 80	%) t ₂₊	2	1.5	4.3	1.5	2.0	3.9	1.5	4.3	
Fall Time (20 to 80	%) t ₂₋	2	1.5	4.3	1.5	2.0	3.9	1.5	4.3	

ELECTRICAL CHARACTERISTICS (continued)

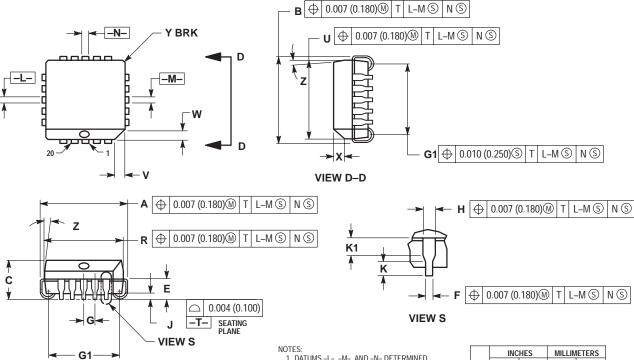
					TEST VO	LTAGE VALU	JES (Volts)		
@ Test Temperature –30°C			V _{IHmax}	V _{ILmin}	VIHAmin	V _{ILAmax}	VEE		
			-0.890	-1.890	-1.205	-1.500	-5.2		
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
Pin			TEST V	OLTAGE AP	PLIED TO P	INS LISTED I	BELOW		
Characteri	istic	Symbol	Under Test	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	VEE	(VCC)
Power Supply Drain C	Current	ΙΕ	8						1, 16
Input Current		linH	3 5	3 5				8 8	1, 16 1, 16
		l _{inL}	3		3			8	1, 16
Output Voltage	Logic 1	Vон	2 15	3, 4, 5 14				8 8	1, 16 1, 16
Output Voltage	Logic 0	V _{OL}	2 15	4, 5 13, 14				8 8	1, 16 1, 16
Threshold Voltage	Logic 1	Vона	2 15			5 13		8 8	1, 16 1, 16
Threshold Voltage	Logic 0	VOLA	2 15				5 13	8 8	1, 16 1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	-3.2 V	+2.0
Propagation Delay		t ₁₃₊₁₅₊ t ₁₄₋₁₅₋ t ₃₊₂₋ t ₃₋₁₅₊	15 15 2 15			13 14 3 3	15 15 2 15	8 8 8	1, 16 1, 16 1, 16 1, 16
Rise Time	(20 to 80%)	t ₂₊	2			3	2	8	1, 16
Fall Time	(20 to 80%)	t ₂ _	2			3	2	8	1, 16

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

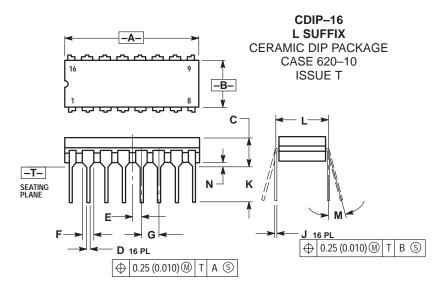
- DATUMS -L-, -M-, AND -N- DETERMINED
 WHERE TOP OF LEAD SHOULDER EXITS PLASTIC WILLY LOVE LEAD STOUDER EXTRA FRAST BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250)
- PER SIDE.
 4. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Ε	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
V	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Χ	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10 °	2 °	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

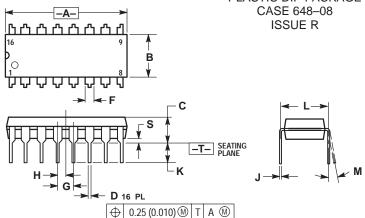
PACKAGE DIMENSIONS



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

	INC	HES	MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Ε	0.050	BSC	1.27 BSC		
F	0.055	0.055 0.065		1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62	BSC	
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.

 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

 5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN	MIN MAX		MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10 °	0 °	10 °	
S	0.020 0.040		0.51	1.01	

Notes

Notes

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